

The Invention is Claimed to be:

1. A method of forming an electronic assembly comprising:
 - (a) providing a first substrate having a plurality of conductive contacts;
 - (b) providing a second substrate having a plurality of conductive contacts;
 - (c) positioning the first and second substrates with their respective conductive contacts in alignment;
 - (d) sandwiching an uncured anisotropic conductive material between the conductive contacts of the first and second substrates, the anisotropic conductive material including electrically conducting material suspended in a binder;
 - (e) heating the anisotropic conductive material to a curing temperature for an interval sufficient to cause the binder to cure to a solid;
 - (f) vibrating the electrically conducting material; and
 - (g) subjecting the electrically conducting material to a static, substantially homogeneous DC magnetic field, wherein the DC magnetic field has a field vector direction that is substantially parallel with the alignment of the conductive contacts of the first and second substrates.
2. The method of claim 1, wherein step (f) includes vibrating the electrically conducting material utilizing at least one of mechanical vibration and a magnetic field.
3. The method of claim 1, wherein, in step (f), the electrically conducting material is vibrated at a frequency in the ultrasonic frequency range.
4. The method of claim 1, wherein at least one of step (f) and step (g) is performed during step (e).
5. The method of claim 1, wherein at least one of the first and second substrates is an electronic component.
6. The method of claim 1, wherein step (f) occurs before step (g), or vice versa.

7. The method of claim 1, wherein step (f) and step (g) occur at least partially concurrently.
8. A method of forming an electronic assembly comprising:
 - (a) sandwiching an uncured anisotropic conductive material between at least one pair of aligned conductive contacts, the anisotropic conductive material including electrically conducting material suspended in a binder;
 - (b) causing the binder to cure to a solid;
 - (c) vibrating the electrically conducting material; and
 - (d) during curing of the binder to a solid, subjecting the electrically conducting material to a static, substantially homogeneous DC magnetic field, wherein the DC magnetic field has a field vector direction that is substantially parallel with the alignment of the pair of conductive contacts.
9. The method of claim 8, wherein step (c) includes vibrating the electrically conducting material at least one of mechanically and via a magnetic field.
10. The method of claim 8, wherein at least one of step (c) and step (d) is performed during curing of the binder to a solid.
11. A method of forming an electronic assembly comprising vibrating conductive material or particles of an anisotropic conductive compound or material sandwiched between at least two aligned conductive contacts while the anisotropic conductive compound is curing and subjecting the conductive material to a static, substantially homogeneous DC magnetic field (i) before, (ii) following or (iii) at least partially during the time the conductive material is being vibrated.
12. The method of claim 11, wherein the conductive material or particles are vibrated at least one of mechanically and via a magnetic field.